

POLOS[®] HOTPLATE 200

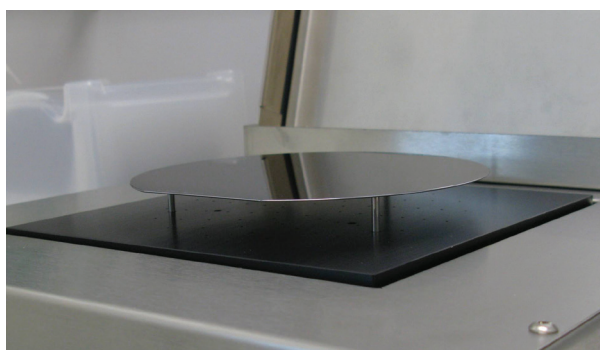
Our all NEW table-top hotplate is a versatile and affordable tool for R&D and pilot lines. It is designed with a hinged lid with N2 connector and is suitable for soft bake as well as hard bake processes, and curing of photoresist, epoxy or any other work requiring precise temperature control. The POLOS[®] Hotplate 200 also has upgradeable options, including lifting pins, vacuum bake and proximity pins.



Also available with a
350 x 350 mm heating area!

HOTPLATE 200 STANDARD

- Temperature Range 50 - 230°C
- Programmable storage of 20 programs (Temperature/Time)
- Countdown timer (1-999 sec.) with acoustic alarm
- Temperature Uniformity $\pm 1^\circ\text{C}$
- Heater Surface Area 220 x 220 mm
- Suitable for 1 x 200 mm Wafer
- Power: max. 1200 W (approx. 550 W to remain at 200°C)
- Voltage: 230 or 110 VAC
- Heater Block Material: Aluminum (anodized)
- Housing Material: Stainless Steel
- Including Hinged Lid with N2 connection
- Weight: 12 kg
- Dimensions: approx. 450 x 320 x 135 mm
- *dims. are without hinged lid



The system is designed to work with process temperatures between 50°C - 230°C.

HOTPLATE 200 ADVANCED

- Temperature Range 50 - 230°C
- Programmable storage of 20 programs (Temperature/Time)
- Countdown timer (1-999 sec.) with acoustic alarm
- Temperature Uniformity $\pm 1^\circ\text{C}$
- Heater Surface Area 220 x 220 mm
- Suitable for 1 x 200 mm Wafer
- Equipped with programmable (electric) Lifting Pins set in radius of 80 mm
- Equipped with Proximity Pins to hold the wafer above the heating plate while baking
- Equipped with perforated vacuum plate to realize a hard contact bake
- Power: max. 1200 W (approx. 550 W to remain at 200°C)
- Voltage: 230 or 110 VAC
- Heater Block Material: Aluminum (anodized)
- Housing Material: Stainless Steel
- Including Hinged Lid with N2 connection
- Weight: 12 kg
- Dimensions: approx. 450 x 320 x 135 mm
- *dims. are without hinged lid

